



September 16, 2015

Datasheet Errata for S6E2D5 Series 32-bit ARM® Cortex®-M4F based Microcontroller

This document describes the errata for the S6E2D5 Series 32-bit ARM® Cortex®-M4F based Microcontroller datasheet. Compare this document to the device's data sheet for a complete functional description.

Contact your local Cypress Sales Representative, if you have questions.

Part Numbers Affected

Part Number	
S6E2D5 Series	

Page	Item	Description							
	Original document code: DS709-00021-1v0-E								
		Rev. 1.0 June 25, 2015							
64	9. Handling Devices	"Sub Crystal Oscillator" should be added as indicated by the shading below. ■Surface mount type Size: More than 3.2 mm × 1.5 mm Load capacitance: Approximately 6 pF to 7 pF When the Standard setting (CCS/CCB=11001110) Load capacitance: Approximately 4 pF to 7 pF When the low power setting (CCS/CCB=00000100) ■Lead type Load capacitance: Approximately 6 pF to 7 pF When the Standard setting (CCS/CCB=11001110) Load capacitance: Approximately 4 pF to 7 pF When the low power setting (CCS/CCB=00000100)							

	14.3.1 Current Rating	Table 14-10 T	ypical and N		l by the shading b	elow.							
	ixatilig			lovimum									
		RTC Mode ar	Table 14-10 Typical and Maximum Current Consumption in Deep Standby Stop Mode, D										
			RTC Mode and VBAT							1			
		Parameter	Symbol	Pin Name	Conditions	Frequency (MHz)	Value Typ	Max	Unit	Remarks			
							0.009	0.032	μА	*3, *4, *5 T _A =+25°C			
					RTC stop		-	0.994	μА	*3, *4, *5 T _A =+85°C			
							-	1.491	μΑ	*3, *4, *5 T _A =+105°C			
		Power					1.0	1.636	μΑ	*3, *4 T _A =+25°C			
	supply		ICCVBAT	VBAT	RTC *6 operation	-	-	2.828	μА	*3, *4 T _A =+85°C			
							-	4.242	μА	*3, *4 T _A =+105°C			
					RTC *7 operation		0.7	1.153	μΑ	*3, *4 T _A =+25°C			
							-	2.277	μΑ	*3, *4 T _A =+85°C			
		*1: V _{CC} =3.3 V					-	3.416	μΑ	*3, *4 T _A =+105°C			
	15. Ordering Information	When the Sta *7: When using When the low	ndard setting (the crystal ose power setting	CCS/CCB= cillator of 3 g (CCS/CCI	32 kHz (including	the current consu	imption of						
		(Error)			T	Destruction							
			Part Number Package S6E2D55G0AGV20000 Plastic • LOEP (0)										
			6E2D55G0AC 6E2D55GJAN		Plastic • (FPT-120	LQFP (0.5 mm p	itch), 120						
			6E2D55J0AG	,	itch), 176								
		S	6E2D55G0AC	GB30000		PFBGA (0.5 mm	pitch), 10						
		S	6E2D55G0AC	GZ20000		Plastic • Ex-LQFP (0.5 mm pitch), 120 pin (LEM120)							
		(Correct)	prrect)										
		P	art Number		Package	Package							
		S	6E2D55G0A0	GV20000	Plastic •	LQFP (0.5 mm p	itch), 120	pin					
		S	6E2D55GJAN	4V20000	(FPT-120	0P-M21)							
		S	S6E2D55J0AGV20000 Plastic • LQFP (0.5 mm) (FPT-176P-M07)					pin					
		S	6E2D55G0AC		Plastic • PFBGA (0.5 mm pitch), 161 pin (FDJ161)								
l			6E2D55G0A0	GE20000	Plastic • (LEM12	Ex-LQFP (0.5 m	m pitch),	120 pin					

Page	Item	Description									
11	2. Features	Note should be added as indicated by the shading below.									
		(Error) GDC Unit Controller for external graphics display Accelerator for 2D block image transfer (blit) operations Embedded SRAM video memory High-Speed Quad SPI (Serial Peripheral Interface for external memory extensions) SDRAM interface for external memory extensions HBI (Hyper Bus Interface) interface for external memory extensions Maximum core system clock frequency: 160 MHz (Correct) GDC Unit Controller for external graphics display Accelerator for 2D block image transfer (blit) operations Embedded SRAM video memory High-Speed Quad SPI (Serial Peripheral Interface for external memory extensions) SDRAM interface for external memory extensions HBI (Hyper Bus Interface) interface for external memory extensions Maximum core system clock frequency: 160 MHz Note:									
		User can leverage the internal VRAM and external Hyp	oerRAM as a graphics	memory allowed to	be written by GDC.						
15	4. Packages	"Packages" should be corrected as indicated by the shad	ding below.								
		(Error)									
		Product Name Package	S6E2D55G0A	S6E2D55J0A	S6E2D55GJA						
		LQFP: FPT-120P-M21 (0.5 mm pitch)	0	-	0						
		LQFP: FPT-176P-M07 (0.5 mm pitch)	-	0	-						
		PFBGA: FDJ161 (0.5 mm pitch)	0	-	-						
		Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)	Q								
		O: Supported	l	<u> </u>							
		(Compat)									
		(Correct) Product Name Package	S6E2D55G0A	S6E2D55J0A	S6E2D55GJA						
		LQFP: FPT-120P-M21 (0.5 mm pitch)	0	_	0						
		LQFP: FPT-176P-M07 (0.5 mm pitch)	-	0	1-						
		FBGA: FDJ161 (0.5 mm pitch)	0	-	-						
		Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)		1	1						
		O: Supported \(\sigma\): In development									
16, 18	5. Pin Assignment	Signal name should be corrected as below. (Error) GE_SPCSX_0 (Correct) GE_SPCSX_0 (Error) GE_HBCSX_0 (Correct) GE_HBCSX_0 (Error) GE_HBCSX_1 (Correct) GE_HBCSX_1									
21, 23, 48	6. Pin Descriptions	Signal name should be corrected as below. (Error) GE_SPCSX_0 (Correct) GE_SPCSX_0 (Error) GE_HBCSX_0 (Correct) GE_HBCSX_0 (Error) GE_HBCSX_1 (Correct) GE_HBCSX_1									

Page	Item	Description								
67	10. Block Diagram	Signal name should be corrected as below. (Error) GE_SPCSX_0 (Correct) GE_SPCSX0 (Error) GE_HBCSX_0/1 (Correct) GE_HBCSX_0/1								
93	14.3 DC Characteristics	"VFLASH memory Standby current" should be corrected as indicated by the shading below. (Error)								
		Parameter	Symbol	Pin name	Conditions	Value Min	т	M	Unit	Remarks
		VFLASH memory Standby current		name	At Standby	-	Тур 15	Max 25	μΑ	
		VFLASH memory	I _{CCVFLASH}	VCC	At Read	_	9	14	mA	40MHz
		Read current	ICCVFLASH	\vec			13	20	ma	80MHz
		VFLASH memory write/erase current			At Write/Erase	-	20	25	mA	
		(Correct)								
		Parameter	Symbol	Pin name	Conditions	Value	Tr	M	Unit	Remarks
		VFLASH memory Standby current		Hame	At Standby	Min -	Тур 15	Max 35	μА	
		VFLASH memory Read current	I _{CCVFLASH}	VCC	At Read	-	9	14	mA	40MHz
		VFLASH memory write/erase current			At Write/Erase	-	13 20	20	mA	80MHz
162, 161, 162	14.4 AC Characteristics	Signal name should be (Error) GE_SPCSX_0 (Error) GE_HBCSX_0 (Error) GE_HBCSX_1	(Correct) GE (Correct) GF	_SPCSX0 E_HBCSX(

Document History Page

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Rev. ECN No. Change Description of Change								
**	_	AKIH	Initial release					
*A	5037589	AKIH	Converted to Cypress format					

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